AMENDMENTS TO THE CLAIMS

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Cancelled).

2. (Previously Presented) The sensor device according to claim 4, wherein the material of said sensor body, said upper sealing member and said lower sealing member is semiconductor.

3. (Previously Presented) The sensor device according to claim 4, wherein said upper sealing member and said lower sealing member house said sensor body in an airtight manner.

4. (Currently Amended) A sensor device comprising:

a sensor body;

an upper sealing member made of the same material as that of said sensor body;

a lower sealing member made of the same material as that of said sensor body, said lower sealing member being joined to said upper sealing member so as to house said sensor body therewithin in cooperation with said upper sealing member;

a mounting electrode disposed on an outer surface of at least one sealing member selected from said upper sealing member and said lower sealing member; ~~and~~

a conductive through-path penetrating through said at least one sealing member to electrically connect between said mounting electrode and said sensor body, and

an insulating film disposed between said at least one sealing member and said conductive through-path.

5. – 6. (Cancelled).

7. (Previously Presented) The sensor device according to claim 4, wherein either one or each of said upper sealing member and said lower sealing member is an integrated circuit board formed with a circuit for driving said sensor body.

8. (Previously Presented) A sensor system comprising:

the sensor device as defined by claim 4; and

an integrated circuit for driving said sensor device.

9. (Previously Presented) The sensor system according to claim 8, which further includes:

a molded interconnect device substrate interposed between said sensor device and said integrated circuit to support each of said sensor device and said integrated circuit in a stacked manner, and adapted to relay the electrical connection between said sensor device and said integrated circuit; and

a mounting external electrode provided in said molded interconnect device substrate and electrically connected to at least either one of said sensor device and said integrated circuit through said molded interconnect device substrate.

10. (Previously Presented) The sensor system according to claim 8, wherein said integrated circuit and said sensor device are joined together to form a stacked body, wherein said sensor system further includes:

a molded interconnect device substrate supporting said stacked body without interposing between said sensor device and said integrated circuit; and

a mounting external electrode provided in said molded interconnect device substrate and electrically connected to at least either one of said sensor device and said integrated circuit through said molded interconnect device substrate.

11. (Previously Presented) The sensor system according to claim 9, wherein said mounting external electrode is a stepwise bent pin.

12. (Original) The sensor system according to claim 8, wherein said integrated circuit and said sensor device are joined together to form a stacked body, wherein said sensor system further includes a mounting external electrode provided in said stacked body.

13. (Currently Amended) The sensor system according to claim 12, wherein:

said mounting external electrode is disposed on one surface of said integrated circuit on the opposite side of the other surface thereof facing to said sensor device; and

said integrated circuit includes an integrated circuit board formed with a circuit for driving said sensor device, and a ~~second~~ wiring pattern extending along a side surface of said integrated circuit board to electrically connect between said mounting external electrode and said sensor device.

14. (Original) The sensor system according to claim 12, wherein:

said mounting external electrode is disposed on one surface of said sensor device on the opposite side of the other surface thereof facing to said integrated circuit; and

said sensor device includes a second wiring pattern extending along respective side surfaces of said upper and lower sealing members to electrically connect between said mounting external electrode and said integrated circuit.

15. (Previously Presented) A method of manufacturing the sensor device according to claim 4, comprising:

forming a through-hole in said at least one sealing member; and

embedding a conductive material in said through-hole to form said conductive through-path.

16. (Previously Presented) The method according to claim 15, wherein said embedding includes:

depositing said conductive material on a surface of said through-hole; and

depositing said conductive material to allow said through-hole to be entirely filled therewith.

17. (Cancelled).

18. (Previously Presented) A method of manufacturing the sensor system according to claim 9, comprising forming a portion electrically connecting between said molded interconnect device substrate and either one of said sensor device and said integrated circuit, at normal temperature.